

SSM P/N HDR01835

Notes.

1. Finish

Full gold 1.27umMIN. over 2.54umMIN. electrolytic nickel under plating.

- 1) Plating thickness : controlled on top of post.
- 2) Measuring method : X-ray fluorescence machine.

2. Inspection(10Kpcs/1Lot)

Inspection Item	Test Condition	Failure Criteria	Sampling
Visual	X20 Microscope, inspect only plating items	No stain, Contamination, peeling, foreign material on plating surface Spec. : Level G , AQL0.65I Internal control : (0,1)	200pcs/Lot
High temperature test	Bake at 450°C±5°C in dry air for 3minutes	No blister, peeling, gross discoloration on plating surface by microscope	10pcs/Lot
Mandrel test	Each lead shall be wrapped tightly around a mandrel of $\phi 1.0 \pm 0.05$	The gold or nickel plating must show no evidence of flaking or gross cracking	5pcs/Lot
Wire bond test	U/S-T/S bond with $\phi 25\mu\text{m}$ gold wire (Use og high temperature test sample)	Bond strength : 3.0gMIN.	5pcs/Lot

						MATERIAL	FINISH	NOTE
REV	DATE	DSGN	CHECK	APPR	D E S C R I P T I O N			
	DATE	DESIGNED	DRAWN	CHECKED	APPR'D	TITLE		
						HEADER, TO-18(3LEAD)		
					PROJ 3RD ANGLE	SCALE	DRAWING NO.	
							KR5509 3/3	

